

ABSTRACT

5 An interconnect for attaching a module such as a PCB or a multi-chip
module to a circuit substrate comprises a member elongated in a
longitudinal direction. The member has at least a first elongated side and
a second opposed and generally parallel elongated side. The first and
second sides extend in the longitudinal direction. Each of the first and
10 second sides have at least one portion formed by a series of depressions
in the respective first and second sides. The depressions extend inwardly
from a first outer surface of the first side and a second outer surface of the
second side. The depressions are metallized to form leads. A circuit
assembly is also provided comprising a multi-chip module having a
15 plurality of electronic elements; a circuit substrate supporting thereon a
conductive circuit pattern adapted for connection to the multi-chip module
and at least one the interconnects for attaching the multi-chip module to
the circuit pattern on the circuit substrate. A process for making the
interconnect and a process for assembling the circuit assembly is also
provided.

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